

SEMICONDUCTOR PACKAGE INCLUDING FLIP CHIP
ABSTRACT OF THE DISCLOSURE

[0020] A semiconductor package comprising a plurality of leads. Each of the leads defines opposed first and second surfaces. Also included in the semiconductor package is a semiconductor chip which defines opposed first and second surfaces, and includes a plurality of input/output pads disposed on the first surface thereof. A plurality of conductive bumps are used to electrically connect the input/output pads of the semiconductor package to the second surfaces of respective ones of the leads. An encapsulant portion of the semiconductor package covers the semiconductor chip, the conductive bumps, and the second surfaces of the leads such that at least portions of the first surfaces of the leads are exposed within the encapsulant portion.